

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claims 1-18 (Canceled)

19. (Original) A shielded interconnect structure for interconnecting plural devices on a printed circuit board, the shielded interconnect structure comprising:

plural first level conductive traces, disposed on an upper surface of the printed circuit board, each first level conductive trace being adapted for electrical connection to one or more of the plural devices;

plural second level conductive traces; disposed on a buried level of the printed circuit board;

plural micro-vias providing electrical connection from selected ones of the first level conductive traces to selected ones of the second level conductive traces;

one or more third level conductive traces, disposed on a further buried level of the printed circuit board;

plural buried vias providing electrical connection from the third level conductive traces to certain ones of the second level conductive traces;

a conductive shield comprising;

a top shield layer disposed on an upper surface of the printed circuit

board, a conductive side wall, electrically connected to the top shield layer, and

a bottom shield layer, electrically connected to the conductive side wall, buried within the printed circuit board at a level beneath the further buried level;

wherein a trench is formed in the printed circuit board surrounding the first level conductive traces, the second level conductive traces, and the third level conductive traces, the conductive side wall being formed on a wall of the trench.

20. (Original) The shielded interconnect structure of claim 19, wherein the top shield layer, the conductive side wall, and the bottom shield layer are formed so that the conductive shield is a unitary Faraday cage surrounding the second level conductive traces and the third level conductive traces.

21. (Original) The shielded interconnect structure of claim 19, wherein the conductive shield and the first, second, and third level conductive traces are formed substantially of copper.

Claims 22-23 Canceled.